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- a) providing a substrate that in an at-rest position has a substantially three-dimensional electrically conductive surface;
 - b) applying a coating of electrophoretic photoresist to the electrically conductive surface by passing an electrical current therethrough;
 - c) exposing the photoresist to a suitable source of electromagnetic radiation through a mask whose shape conforms closely to that of the substrate;
 - d) developing the photoresist; and
 - e) electrodepositing a metallic layer onto conductive surface regions of the substrate not coated with the photoresist.
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25. (Once Amended) A method according to claim 22 further comprising providing the mask with a plurality of non-elongate apertures.

26. (Once Amended) A method according to claim 25 wherein each of the plurality of apertures has a diameter in the range 600 to 800 microns.

27. (Once Amended) A method according to claim 22, further comprising providing the mask with a plurality of elongate apertures.

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28. (Once Amended) A method according to claim 27 wherein each of the plurality of apertures has a length of 400 to 2200 μm and a width of 400 to 800 μm .

29. (Once Amended) A method according to claim 22 wherein the metallic layer has a varying relief pattern.

30. (Once Amended) A method according to claim 22, wherein the mask is made of ductile metal.

31. (Once Amended) A method according to claim 22 further comprising separating the metallic layer from the substrate by at least one of peeling and dissolution of the substrate.

32. (Once Amended) A method of manufacturing a three-dimensional electroforming mask comprising:

providing a mandrel defining a three-dimensional surface; and
forming an electrically conductive surface pattern on the three-dimensional surface, said forming comprising etching using a laser.

33. (Once Amended) A method according to claim 32 wherein the forming of the electrically conductive surface pattern further comprises coating an electrically conductive substrate with photoresist and selectively removing portions of the photoresist using the laser.

34. (Once Amended) A method according to claim 32 wherein the forming of the electrically conductive surface pattern further comprises coating an electrically insulating substrate with a conductive layer, and selectively removing portions of the conductive layer using the laser.

35. (Once Amended) A method according to claim 34 further comprising electroforming the conductive layer to a desired thickness.

36. (Once Amended) A method according to claim 35 wherein the etching step is followed by electroforming of the conductive layer to the desired thickness.

37. (Once Amended) A method according to claim 34, further comprising removing the coating from the substrate.

Add claims 38-40.

38. (New) A method according to claim 22, wherein the surface has a non-zero Gaussian curvature.

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39. (New) A method according to claim 22, wherein the mask is made of copper.

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40. (New) A method according to claim 34 wherein the coating of electrophoretic photoresist has a substantially uniform thickness.

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